



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2015-02-13
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Giovanni Giacopello	Representative Title	AMS & IPD Materials Declaration Champion
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/internet/com/support/online_tech_support.jsp		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	7AVP*206HMM1	A	SH1A	2015-02-13
Amount	UoM	Unit type	ST ECOPACK Grade	
1900.00	mg	Each	ECOPACK® 1	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
NAC	NAC	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used o	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SIP	10.2,15.5,4.5	3	Through-hole	
Comment	Package: TO 220 NI CLIP; MDF valid for TN2015H-6T			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	false
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)
7c-I	Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devic

QueryList : REACH-17th December 2014				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	7AVP*206HMM1					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
die (s)	Other inorganic materials	6.412	mg	supplier	die	Silicon (Si)	7440-21-3		5.703	mg	889426	3002
die (s)				supplier	metallization	Nickel (Ni)	7440-02-0		0.072	mg	11229	38
die (s)				supplier	metallization	Gold (Au)	7440-57-5		0.016	mg	2495	8
die (s)				supplier	passivation	Alumina	1344-28-1		0.046	mg	7174	24
die (s)				supplier	passivation	Lead silicate Glass	65997-18-4	7c-I-Electrical and e	0.413	mg	64410	217
die (s)				supplier	back side metallization	Gold (Au)	7440-57-5		0.007	mg	1092	4
die (s)				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.155	mg	24173	82
Leadframe	Copper & its alloys	1627.643	mg	supplier	alloy	Copper (Cu)	7440-50-8		1626.015	mg	999000	855797
Leadframe				supplier	alloy	CopperPhosphorous (CuP)	12517-41-8		1.628	mg	1000	857
Soft solder	Solder	3.358	mg	JIG R	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	3.14	mg	935080	1653
Soft solder				supplier	solder	Silver (Ag)	7440-22-4		0.05	mg	14890	26
Soft solder				supplier	solder	Tin (Sn)	7440-31-5		0.168	mg	50030	88
Clip	Other inorganic materials	31.625	mg	supplier	clip	Copper (Cu)	7440-50-8		35.509	mg	1000000	18689
encapsulation	Other Organic Materials	220.764	mg	supplier	mold compound	Silica, vitreous	60676-86-0		180.008	mg	815387	94741
encapsulation				supplier	mold compound	Phenol resin	9003-35-4		12.13	mg	54946	6384
encapsulation				supplier	mold compound	Carbon black	1333-86-4		1.94	mg	8788	1021
encapsulation				supplier	mold compound	Epoxy Cresol Novolak	29690-82-2		26.686	mg	120880	14045
connections coating	Solder	6.314	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		6.314	mg	1000000	3323